

BRBSS84Q

Rev.A Mar.-2023



SOT-23 P-CHANNEL MOSFET in a SOT-23 Plastic Package.

Low threshold voltage, Direct interface to C-MOS, TTL etc, High-speed switching,ESD Improved

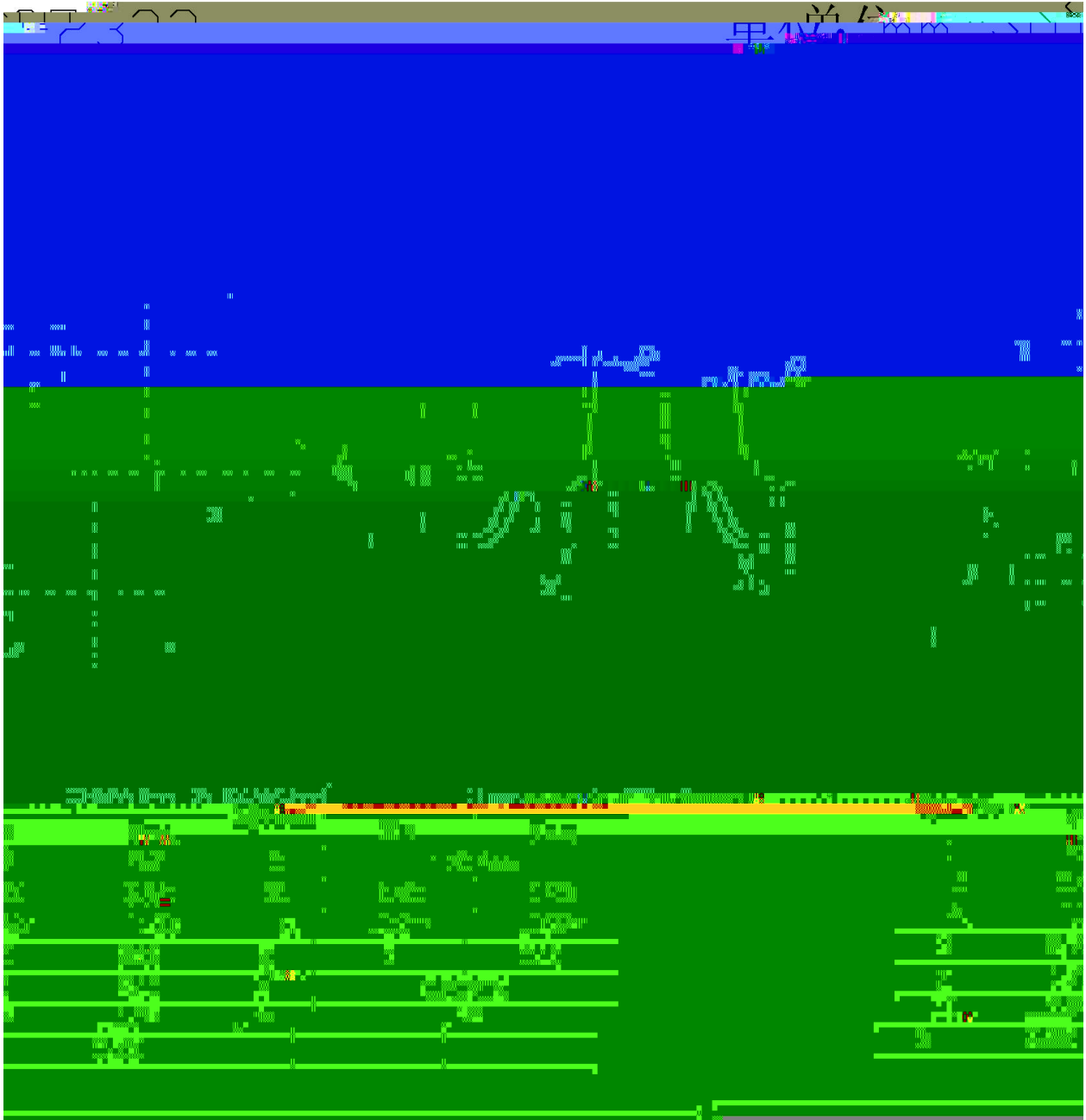
Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DSS}	-50	V
Drain Current – Continuous	I_D	-130	mA
Peak Drain Current	I_{DM}	-520	mA
Gate-Source Voltage	V_{GSS}	± 20	V
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	500	/W
Storage Temperature Range	T_{stg}	-65 to 150	
Junction Temperature Range	T_j	150	

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Drain–Source Breakdown Voltage	V_{DSS}	$V_{GS}=0V$ $I_D=-10\mu A$	-50			V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}$ $I_D=-250\mu A$	-0.8		-2.0	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{GS}=0V$ $V_{DS}=-40V$			-100	nA
		$V_{GS}=0V$ $V_{DS}=-50V$			-10	μA

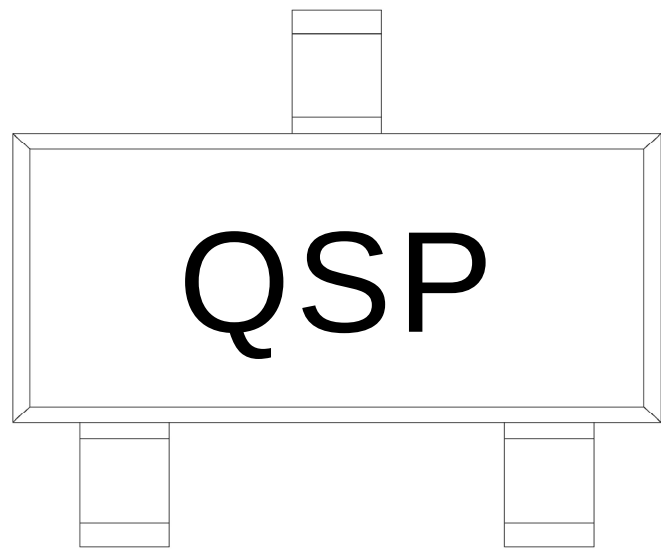
/ Electrical Characteristic Curve



/ Package Dimensions



/ Marking Instructions



” X
T X n ñ β %
SP X ³ N .

Note:
Q: Automobile halogen-free product Code
SP: Product Type.

() / Temperature Profile for IR Reflow Soldering(Pb-Free)

- ” X
- Note:
1. Preheating: 150~200 , Time: 60~120sec.
 2. Peak Temp.: 255±5 , Duration: 5±0.5sec.
 3. Cooling Speed: 2~10 /sec.

/ Resistance to Soldering Heat Test Conditions

□ ý χ 260±5 `H χ 10±1 sec. Temp.: 260±5 Time: 10±1 sec

/ Packaging SPEC.

□` γ / REEL

Package Type